Materials Declaration

Package	TQFP - EP
Body Size	14 X 14 X 1.0
LeadCount	80
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	88	2.80 E-01	514410
Multi-aromatic Resin	11.5	3.65 E-02	67224
Carbon Black	0.5	1.59 E-03	2923
Subtotal		3.18 E-01	584558

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.45	1.77 E-01	326086
FE	2.4	4.37 E-03	8031
Zn	0.12	2.18 E-04	401
P	0.03	5.50 E-05	101
Subtotal		1.82 E-01	334619

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	8.00 E-04	1472

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.39 E-02	25570

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	2.80 E-03	5151

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.21 E-02	40625

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70	3.05 E-03	5604
Resin	20	8.70 E-04	1601
Anhydride	10	4.35 E-04	800
Subtotal		4.35 E-03	8005

Molding Compound

Item	PPM	Method
Pb	None Detected	USEPA 3052. ICP-AES.
Cd	None Detected	USEPA 3052. ICP-AES.
Hg	None Detected	USEPA 3052. ICP-AES or USEPA 7473. Hg Analyzer.
Cr+6	None Detected	USEPA 3060A & 7196A.
PBB	None Detected	USEPA 8081A/8270D/3540C/3550C. Analysis by GC/MS.
PBDE	None Detected	USEPA 8081A/8270D/3540C/3550C. Analysis by GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	None Detected	USEPA 3052. ICP-OES
Cd	None Detected	USEPA 3052. ICP-OES
Hg	None Detected	USEPA 3052. ICP-OES
Cr+6	None Detected	USEPA 3060A & 7196A. UV-VIS.
PBB	None Detected	Analysis was performed by GC/MS.
PBDE	None Detected	Analysis was performed by GC/MS.

Package Totals

Weight (g)	PPM
5.44 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary